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U.S. PATENT DOCUMENTS

*Examiner Initial		Document Number	Date	Name	Class	Subclasses	Filing Date if Appropriate
<i>QNB</i>	AA	6,107,109	8/22/00	Akram et al.	<i>138</i>	<i>15</i>	<i>X</i>
<i>QNB</i>	AB	6,114,240	9/5/00	Akram et al.	<i>434</i>	<i>667</i>	<i>X</i>
<i>QNB</i>	AC	6,294,837	9/25/01	Akram et al.	<i>257</i>	<i>774</i>	<i>X</i>
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclasses	Translation	
							Yes	No
	AK							
	AL							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

<i>QNB</i>	AM	<i>X</i>	Electroless Plating; http://www.corrosion-doctors.org/MetalCoatings/Electroless.htm ; 12/5/2003; pp. 1-4
<i>QNB</i>	AN		Electroless Plating; http://www.corrosion-doctors.org/MetalCoatings/Electroless.htm ; 10/20/2003; pp. 1-2
<i>QNB</i>	AO		Slide Show: "Through-Wafer Copper Electroplating for RF Silicon Technology"; N.T. Nguyen et al.; DIMES - TU Delft, Netherlands; http://www.essderc2002.dais.unibo.it/ESSDERC_web/Session_D11/D11_2.pdf
<i>QNB</i>	AP	<i>X</i>	"Atomic Layer Deposition of TIN Films by Alternate Supply of Tetraakis(ethylmethylamino)-Titanium and Ammonia"; Son, et al.; Jpn. J. Appl. Phys. Vol. 37 (1998) pp. 4999-5004; Part 1, No. 9A; September 1998 Japanese Journal of Applied Physics
			: Jae-Sik Min, Young-Woong

EXAMINER

William M. Brewster

DATE CONSIDERED

26 Nov 04

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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9/B	AM	X	*Kinetic modeling of film growth rates of TiN films in atomic layer deposition; Jung-Wook Lim et al. Journal of Applied Physics; Vol. 87, No. 9; 1 May 2000; pp. 4632-4634				
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	AN						
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EXAMINER <u>William M. Brown</u>				DATE CONSIDERED <u>26 Nov 01</u>			
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